

**IN THE CLAIMS:**

Please cancel claims 1-3 and 6-12 without prejudice.

Kindly amend claim 4 and add new claims 13-16 as follows.

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1 -3. (Canceled)

4. (Presently Amended) A method for forming patterns, which comprises the steps of:

applying a photosensitive resin composition onto a substrate and drying;

exposing the composition using i-lines line monochromatic light as a light source by an i-line stepper;

developing the composition; and

heating the composition, wherein:

the substrate is a silicon wafer having a diameter of at least 12 inches;

the photosensitive resin composition comprises an aromatic polyimide precursor wherein a 10  $\mu$ m thick layer of the aromatic polyimide precursor has a light transmittance at a wavelength of 365 nm of at least 1%, and a 10  $\mu$ m thick polyimide film made from the resin composition by imidation ring closure and deposited on a silicon substrate has a residual stress of at most 25 MPa; wherein and

the photosensitive resin composition is selected from the group consisting of (1) a negative-type photosensitive resin composition where the aromatic polyimide precursor comprises a repetitive unit having a monovalent organic group with a carbon-carbon unsaturated double bond on at least a part of side chains of carboxylic acid residues, and (2)